

What is claimed is:

1. A frame for semiconductor package comprising plural lead frames arranged in matrix through grid-leads, the grid-leads having terminals projected from the grid-leads, in which respective semiconductor devices are mounted on die-pads supported with suspending leads of individual lead frames, the semiconductor devices are collectively molded with molding compound, and the collectively molded semiconductor devices are cut into individual semiconductor packages at grid-frames, wherein thin parts are formed in areas corresponding to neighborhood of the roots of individual terminals.

2. A frame for semiconductor package as claimed in claim 1, wherein the thin parts are formed by half-cutting by etching metal of the areas from the front or back thereof.

3. A frame for semiconductor package comprising plural lead frames arranged in matrix through grid-leads, the grid-leads having terminals projected from the grid-leads, in which respective semiconductor devices are mounted on die-pads supported with suspending leads of individual lead frames, the semiconductor devices are collectively molded with molding compound, and the collectively molded semiconductor devices are cut into individual semiconductor packages at grid-frames, wherein hollows are formed in areas corresponding to neighborhood of the roots of individual terminals.